Special Issue

Image and Signal Processing in Biomedical Engineering

Message from the Guest Editor

Most of the unstructured medical data is occupied by image and signal data, and processing these types of data is a major field in biomedical engineering. Especially recently, methods of processing image and signal are rapidly developing with the development of machine learning and deep learning techniques. Therefore, the purpose of this Special Issue is intended for the presentation of novel ideas, and to present studies that have verified the results through experiments in application fields using medical image and signal data. Areas relevant to image and signal processing in biomedical engineering, but are not limited to, computer aided diagnosis, applications of big data in medicine, artificial intelligence, machine learning and deep learning and other sources.

Guest Editor

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Message from the Editor-in-Chief

As the world of science becomes ever more specialized, researchers may lose themselves in the deep forest of the ever increasing number of subfields being created. This open access journal Applied Sciences has been started to link these subfields, so researchers can cut through the forest and see the surrounding, or quite distant fields and subfields to help develop his/her own research even further with the aid of this multi-dimensional network.

Editor-in-Chief

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